

Title (en)

CLAD MATERIAL, METHOD FOR MANUFACTURING SAID CLAD MATERIAL, AND APPARATUS FOR MANUFACTURING SAID CLAD MATERIAL

Title (de)

BESCHICHTUNGSMATERIAL, VERFAHREN ZUR HERSTELLUNG DES BESCHICHTUNGSMATERIALS UND VORRICHTUNG ZUR HERSTELLUNG DES BESCHICHTUNGSMATERIALS

Title (fr)

MATERIAU PLAQUE, METHODE POUR FABRIQUER LEDIT MATERIAU ET APPAREIL POUR FABRIQUER LEDIT MATERIAU PLAQUE

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2005077569A1] A method for manufacturing a clad material in which a core material is cast and skin materials are pressure-bonded thereon aims to prevent deterioration of adhesiveness of the core material and the skin materials while keeping sufficient cooling rate of the core material, prevent thickness variation and/or breakage of the skin materials during the manufacturing process, and keep the surface property of the cooling rolls constant. The method for manufacturing a clad material (11) includes the steps of continuously supplying molten metal (M) into a gap between a pair of cooling rollers (2a) (2b) to cast a core material, and cladding skin materials (10a) (10b) on both surfaces of the core material with hot rolling by continuously supplying the skin materials on peripheral surfaces of the cooling rollers so that the skin materials prevent direct contact between the cooling rollers and the molten metal, wherein the skin materials are supplied so as to come into contact with the peripheral surfaces of the cooling rollers, and wherein a contact distance (L1) from a contact starting point (P1) where the skin material begins to come into contact with the cooling roller to a meeting point (P2) where the skin material begins to come into contact with the molten metal is set to 100 times or more of a thickness (t1) of the skin material.

IPC 8 full level

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